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APPLICATION NO.	FILING DATE	FIRST NAMED INVENTOR	ATTORNEY DOCKET NO.	CONFIRMATION NO.
10/792,101	03/03/2004	Jie Xue	CIS03-69(8041)	4081
47654	7590	08/09/2006	EXAMINER	
DAVID E. HUANG, ESQ. BAINWOOD HUANG & ASSOCIATES LLC 2 CONNECTOR ROAD SUITE 2A WESTBOROUGH, MA 01581			VORTMAN, ANATOLY	
			ART UNIT	PAPER NUMBER
			2835	
DATE MAILED: 08/09/2006				

Please find below and/or attached an Office communication concerning this application or proceeding.

<b>Office Action Summary</b>	<b>Application No.</b>	<b>Applicant(s)</b>	
	10/792,101	XUE ET AL.	
	<b>Examiner</b> Anatoly Vortman	<b>Art Unit</b> 2835	

-- The MAILING DATE of this communication appears on the cover sheet with the correspondence address --  
**Period for Reply**

A SHORTENED STATUTORY PERIOD FOR REPLY IS SET TO EXPIRE 3 MONTH(S) OR THIRTY (30) DAYS, WHICHEVER IS LONGER, FROM THE MAILING DATE OF THIS COMMUNICATION.

- Extensions of time may be available under the provisions of 37 CFR 1.136(a). In no event, however, may a reply be timely filed after SIX (6) MONTHS from the mailing date of this communication.
- If NO period for reply is specified above, the maximum statutory period will apply and will expire SIX (6) MONTHS from the mailing date of this communication.
- Failure to reply within the set or extended period for reply will, by statute, cause the application to become ABANDONED (35 U.S.C. § 133). Any reply received by the Office later than three months after the mailing date of this communication, even if timely filed, may reduce any earned patent term adjustment. See 37 CFR 1.704(b).

#### Status

- 1) Responsive to communication(s) filed on 10 July 2006 (RCE & Amendment).
- 2a) This action is **FINAL**.                            2b) This action is non-final.
- 3) Since this application is in condition for allowance except for formal matters, prosecution as to the merits is closed in accordance with the practice under *Ex parte Quayle*, 1935 C.D. 11, 453 O.G. 213.

#### Disposition of Claims

- 4) Claim(s) 1-12, 14-16 and 21-31 is/are pending in the application.
  - 4a) Of the above claim(s) \_\_\_\_\_ is/are withdrawn from consideration.
- 5) Claim(s) \_\_\_\_\_ is/are allowed.
- 6) Claim(s) 1-12, 14-16 and 21-30 is/are rejected.
- 7) Claim(s) 31 is/are objected to.
- 8) Claim(s) \_\_\_\_\_ are subject to restriction and/or election requirement.

#### Application Papers

- 9) The specification is objected to by the Examiner.
- 10) The drawing(s) filed on \_\_\_\_\_ is/are: a) accepted or b) objected to by the Examiner.  
 Applicant may not request that any objection to the drawing(s) be held in abeyance. See 37 CFR 1.85(a).  
 Replacement drawing sheet(s) including the correction is required if the drawing(s) is objected to. See 37 CFR 1.121(d).
- 11) The oath or declaration is objected to by the Examiner. Note the attached Office Action or form PTO-152.

#### Priority under 35 U.S.C. § 119

- 12) Acknowledgment is made of a claim for foreign priority under 35 U.S.C. § 119(a)-(d) or (f).
  - a) All    b) Some \* c) None of:
    1. Certified copies of the priority documents have been received.
    2. Certified copies of the priority documents have been received in Application No. \_\_\_\_\_.
    3. Copies of the certified copies of the priority documents have been received in this National Stage application from the International Bureau (PCT Rule 17.2(a)).

\* See the attached detailed Office action for a list of the certified copies not received.

#### Attachment(s)

- 1) Notice of References Cited (PTO-892)
- 2) Notice of Draftsperson's Patent Drawing Review (PTO-948)
- 3) Information Disclosure Statement(s) (PTO-1449 or PTO/SB/08)  
 Paper No(s)/Mail Date \_\_\_\_\_.
- 4) Interview Summary (PTO-413)  
 Paper No(s)/Mail Date. \_\_\_\_\_.
- 5) Notice of Informal Patent Application (PTO-152)
- 6) Other: \_\_\_\_\_.

## **DETAILED ACTION**

### ***Continued Examination Under 37 CFR 1.114***

1. A request for continued examination under 37 CFR 1.114, including the fee set forth in 37 CFR 1.17(e), was filed in this application after final rejection. Since this application is eligible for continued examination under 37 CFR 1.114, and the fee set forth in 37 CFR 1.17(e) has been timely paid, the finality of the previous Office action has been withdrawn pursuant to 37 CFR 1.114. Applicant's submission filed on July 7, 2006 has been entered.

### ***Claim Rejections - 35 USC § 102***

2. The following is a quotation of the appropriate paragraphs of 35 U.S.C. 102 that form the basis for the rejections under this section made in this Office action:

A person shall be entitled to a patent unless –

(a) the invention was known or used by others in this country, or patented or described in a printed publication in this or a foreign country, before the invention thereof by the applicant for a patent.

3. Claims 5, 14, 16, 25 and 26 are rejected under 35 U.S.C. 102(a) as being anticipated by Oggioni et al.

Regarding claim 5, Oggioni et al. discloses a circuit board component, comprising: a substrate having non-conductive material and conductive material supported by the non-conductive material (paragraph 0033, 0035), the conductive material defining (i) a circuit board interface, (ii) a die interface, (iii) a heat spreader interface, and (iv) a set of connections which

interconnects the circuit board interface, the die interface and the heat spreader interface, a die coupled to the die interface defined by the conductive material of the substrate (paragraph 0021 and 0022 describe the interconnections between the die, the heat spreader and circuit board interface, since they are electrically connected, the conductive material of the substrate is exposed at the interface, and therefore, defines the interface), the die including integrated circuitry which is configured to electrically communicate with a circuit board when the circuit board couples to the circuit board interface defined by the conductive material of the substrate (paragraphs 0021, 0035), and a heat spreader coupled to the heat spreader interface defined by the conductive material of the substrate, the heat spreader being configured to dissipate heat from the die (paragraph 0004), the heat spreader in combination with the heat spreader interface forming an electromagnetic interference shield when a portion of the circuit board interface connects to a ground reference of the circuit board through the circuit board interface (paragraphs 0009, 0010., figure 3), wherein the die is disposed between the heat spreader and the substrate (fig. 3, 4) and wherein the circuit board component is an Application Specific Integrated Circuit (paragraphs 0015, 0016).

.Regarding claim 14, Oggioni et al. discloses a circuit board component, comprising: a heat spreader configured to dissipate heat from the circuit board component (paragraph 0004), a substrate having non-conductive material and conductive material supported by the non-conductive material (paragraph 0033), the conductive material defining (i) a circuit board interface, (ii) a die interface, (iii) heat spreader connecting means (201) for physically and electrically connecting to the heat spreader, and (iv) a set of connections which interconnects the circuit board interface, the die interface and the heat spreader connecting means (paragraphs

0021, 0022, 0035), wherein the heat spreader and the heat spreader connecting means form an electromagnetic interference shield when a portion of the circuit board interface connects to a ground reference of a circuit board through the circuit board interface (paragraphs 0009, 0010., figure 3), and a die coupled to the die interface defined by the conductive material of the substrate (paragraph 0035), the die including integrated circuitry which is configured to electrically communicate with the circuit board when the circuit board couples to the circuit board interface defined by the conductive material of the substrate (paragraph 0021), wherein the die is disposed between the heat spreader and the substrate (fig. 3, 4) and wherein the circuit board component is an Application Specific Integrated Circuit (paragraphs 0015, 0016).

Regarding claim 16, Oggioni et al. further discloses a heat spreader interface defined by the conductive material of the substrate which includes: conductive ground plates disposed along a flat surface of the substrate, the conductive ground plates encircling the die interface in a 360 degree manner (top surface of PTH's '201' in figure 2 & 3 that contact the heat spreader '401' constitute the conductive ground plane) to minimize escape of electromagnetic interference from the die during operation of the integrated circuitry (Oggioni et al., paragraph 0009).

Regarding claim 25, Oggioni et al. further disclose that the conductive ground plates that are disposed along the flat surface of the substrate define a separation distance between adjacent ground plates (see figure 2).

Regarding claim 26, Ogionni et al. further disclose that the separation distance is less than one-half the length of an electromagnetic wave (although Ogionni et al. does not disclose the distance between the adjacent ground plates, this distance will have to be less than one-half of some electromagnetic wave since electromagnetic waves can exist in any wavelength, see

attached description of the Electromagnetic waves from The Hutchinson Encyclopedia, Helicon Publishing Limited, 2001).

***Claim Rejections - 35 USC § 103***

4. The following is a quotation of 35 U.S.C. 103(a) which forms the basis for all obviousness rejections set forth in this Office action:

(a) A patent may not be obtained though the invention is not identically disclosed or described as set forth in section 102 of this title, if the differences between the subject matter sought to be patented and the prior art are such that the subject matter as a whole would have been obvious at the time the invention was made to a person having ordinary skill in the art to which said subject matter pertains. Patentability shall not be negated by the manner in which the invention was made.

5. Claims 1-4, 6-8, 10-12, 15, 21-24, 27, 28 and 30 are rejected under 35 U.S.C. 103(a) as being unpatentable over Oggioni et al. (PGPub US 2003/0174478) in view of Takeuchi (PGPub US 2003/0122242 A1).

Regarding claim 1, Oggioni et al. discloses a circuit board module, comprising: a circuit board having a component mounting location, a circuit board component mounted to the component mounting location of the circuit board (Figure 3), the circuit board component including: a substrate having non-conductive material and conductive material supported by the non-conductive material (paragraph 0033), the conductive material defining (i) a circuit board interface, (ii) a die interface, (iii) a heat spreader interface, and (iv) a set of connections which interconnects the circuit board interface, the die interface and the heat spreader interface, a die coupled to the die interface defined by the conductive material of the substrate (paragraph 0035), the die including integrated circuitry which is configured to electrically communicate with the circuit board when the circuit board couples to the circuit board interface defined by the

conductive material of the substrate (paragraph 0021, 0035), and a heat spreader coupled to the heat spreader interface defined by the conductive material of the substrate, the heat spreader being configured to dissipate heat from the die (paragraph 0004), the heat spreader in combination with the heat spreader interface forming an electromagnetic interference shield when a portion of the circuit board interface connects to a ground reference of the circuit board through the circuit board interface (paragraphs 0009, 0010, figure 3). Oggioni et al. do not disclose a heat sink in thermal communication with the heat spreader. Takeuchi discloses a heat sink in thermal communication with the heat spreader of a circuit board module (Figure 6). At the time the invention was made, it would have been obvious to one of ordinary skill in the art to incorporate the heat sink in contact with the heat spreader as taught by Takeuchi in the circuit board module as disclosed by Oggioni et al. in order to improve thermal dissipation (Takeuchi, paragraph 0023), wherein the die is disposed between the heat spreader and the substrate (fig. 3, 4) and wherein the circuit board component is an Application Specific Integrated Circuit (paragraphs 0015, 0016).

Regarding claim 2, Oggioni et al. further discloses a heat spreader interface defined by the conductive material of the substrate of the circuit board component which includes a conductive ground plane disposed along a flat surface of the substrate (Top surface of PTH's '201' in figure 2 & 3 that contacts the heat spreader '401' constitute the conductive ground plane) which minimizes the escape of electromagnetic interference from the die during operation of the integrated circuitry (paragraph 0010). Oggioni et al. do not disclose that the conductive ground plane completely encircles the die interface in a 360 degree manner. Takeuchi discloses a ground plane that completely encircles the die in a 360 degree manner (paragraph 0027). At the time the

invention was made, it would have been obvious to one of ordinary skill in the art to incorporate the ground plane that completely encloses the die in a 360 degree manner as taught by Takeuchi in the circuit module as disclosed by Oggioni et al., in order to create a complete EMI shield around the die (Oggioni et al., paragraph 0009).

Regarding claim 3, Oggioni et al. further discloses a circuit board module of claim 1 wherein the heat spreader interface defined by the conductive material of the substrate of the circuit board component includes: conductive ground plates disposed along a flat surface of the substrate, the conductive ground plates encircling the die interface in a 360 degree manner (Top surface of PTH's '201' in figure 2 & 3 that contacts the heat spreader '401' constitute the conductive ground plane) to minimize escape of electromagnetic interference from the die during operation of the integrated circuitry (Oggioni et al., paragraph 0009).

Regarding claim 4, Oggioni et al. discloses a circuit board module, comprising: a circuit board having a component mounting location (Figure 3), a circuit board component mounted to the component mounting location of the circuit board, the circuit board component including: a heat spreader configured to dissipate heat from the circuit board component (paragraph 0004), a substrate having non-conductive material and conductive material supported by the non-conductive material (paragraph 0033), the conductive material defining (i) a circuit board interface, (ii) a die interface, (iii) heat spreader connecting means (201) for physically and electrically connecting to the heat spreader (paragraph 0033), and (iv) a set of connections which interconnects the circuit board interface, the die interface and the heat spreader connecting means (paragraphs 0021 & 0022), wherein the heat spreader and the heat spreader connecting means form an electromagnetic interference shield when a portion of the circuit board interface

connects to a ground reference of the circuit board through the circuit board interface (figure 3, paragraph 0009), and a die coupled to the die interface defined by the conductive material of the substrate, the die including integrated circuitry which is configured to electrically communicate with the circuit board when the circuit board couples to the circuit board interface (paragraph 0021) defined by the conductive material of the substrate. Oggioni et al. do not disclose a heat sink in thermal communication with the heat spreader. Takeuchi discloses a heat sink in thermal communication with the hear spreader of a circuit board module (Figure 6). At the time the invention was made, it would have been obvious to one of ordinary skill in the art to incorporate the heat sink in contact with the heat spreader as taught by Takeuchi in the circuit board module as disclosed by Oggioni et al. to improve thermal dissipation (Takeuchi, paragraph 0023), wherein the die is disposed between the heat spreader and the substrate (fig. 3, 4) and wherein the circuit board component is an Application Specific Integrated Circuit (paragraphs 0015, 0016).

Regarding claim 6, Oggioni et al. satisfy all the limitations of claim 5, and further discloses a heat spreader interface that includes a conductive ground plane disposed along a flat surface of the substrate (top surface of PTH's '201' in figure 2 & 3 that contact the heat spreader '401' constitute the conductive ground plane) which minimizes the escape of electromagnetic interference from the die during operation of the integrated circuitry (paragraph 0010). Oggioni et al. do not disclose that the conductive ground plane completely encircles the die interface in a 360 degree manner. Takeuchi discloses a ground plane that completely encircles the die in a 360 degree manner (paragraph 0027). At the time the invention was made, it would have been obvious to one of ordinary skill in the art to incorporate the ground plane that completely

encloses the die in a 360 degree manner as taught by Takeuchi in the circuit module as disclosed by Oggioni et al., in order to create a complete EMI shield around the die (Oggioni et al., paragraph 0009).

Regarding claim 7, Oggioni et al. as modified by Takeuchi discloses all the limitations of claim 6, and further disclose that the conductive ground plane of the heat spreader extends along an outer periphery of the substrate (figure 4). Oggioni et al. do not disclose a conductive ground edge disposed along the outer periphery of the substrate, the conductive ground edge being contiguous with the conductive ground plane and extending from the conductive ground plane in a substantially perpendicular manner relative to the conductive ground plane to minimize escape of electromagnetic interference from the substrate during operation of the integrated circuitry. Takeuchi et al. discloses a conductive ground edge disposed along the outer periphery of the substrate, the conductive ground edge being contiguous with the conductive ground plane and extending from the conductive ground plane in a substantially perpendicular manner relative to the conductive ground plane (figures 3 & 4) to 'minimize escape of electromagnetic interference from the substrate during operation of the integrated circuitry (paragraph 0004). At the time the invention was made, it would have been obvious for one of ordinary skill in art to incorporate the conductive ground edge disposed along the outer periphery of the substrate with the conductive ground edge contiguous with the conductive ground plane and extending from it in a substantially perpendicular manner, as taught by Takeuchi in the circuit board component of Oggioni et al. in order to be able to incorporate more electrical components under heat spreader and to provide EMI protection for them (Takeuchi, figure 7, paragraph 0025, 0026).

Regarding claim 8, Oggioni et al. further discloses that the heat spreader includes a main portion which extends along the flat surface of the substrate in a substantially parallel manner relative to the flat surface of the substrate, and an edge portion which extends along the outer periphery of the substrate in a substantially parallel manner relative to the outer periphery of the substrate, where the edge portion is contiguous with the main portion. Oggioni et al. do not disclose that the edge portion extends from the main portion in a substantially perpendicular manner relative to the main portion. Takeuchi et al. disclose a heat spreader where the edge portion extends from the main portion in a substantially perpendicular manner relative to the main portion. At the time the invention was made, it would have been obvious to one of ordinary skill in the art to incorporate the heat spreader where the edge portion extends from the main portion in a substantially perpendicular manner relative to the main portion, as taught by Takeuchi in the circuit board component of Oggioni et al. in order to create a complete EMI fence around the die (Oggioni et al., paragraph 0009).

Regarding claim 10, Oggioni et al. as modified by Takeuchi satisfies all the limitations of claim 5, and further disclose that the heat spreader interface includes: conductive ground plates disposed along a flat surface of the substrate, the conductive ground plates encircling the die interface in a 360 degree manner (top surface of PTH's '201' in figure 2 & 3 that contacts the heat spreader '401' constitute the conductive ground plane) to minimize escape of electromagnetic interference from the die during operation of the integrated circuitry (paragraph 0010).

Regarding claim 11, Oggioni et al. do not disclose a ring shaped solder joint formed from high temperature solder which forms an electromagnetic interference seal between the heat

spreader and the heat spreader interface defined by the conductive material of the substrate.

Takeuchi discloses a ring shaped solder joint ('408', paragraph 0019) formed from high temperature solder which forms an electromagnetic interference seal between the heat spreader and the heat spreader interface defined by the conductive material of the substrate (paragraph 0004, 0015).

Regarding claim 12, Oggioni et al. further that discloses the heat spreader interface is disposed along a first flat surface of the substrate (figure 4), wherein the circuit board interface is disposed along a second flat surface of the substrate (figure 2 & 4), wherein the first and second flat surfaces are substantially parallel to each other, wherein the circuit board interface includes an array of pads, and wherein the circuit board component further comprises: an array of circuit board contacts coupled to the array of pads, the array of circuit board contacts being configured to mount to an area array component mounting location of the circuit board using a surface mount technology soldering process (paragraph 0009, 0035).

Regarding claim 15, Oggioni et al. discloses all the limitations of claim 14, and further discloses a heat spreader interface defined by the conductive material of the substrate which includes a conductive ground plane disposed along a flat surface of the substrate (Top surface of PTH's '201' in figure 2 & 3 that contacts the heat spreader '401' constitute the conductive ground plane) which minimizes the escape of electromagnetic interference from the die during operation of the integrated circuitry (paragraph 0010). Oggioni et al. does not disclose that the conductive ground plane completely encircles the die interface in a 360 degree manner. Takeuchi discloses a ground plane that completely encircles the die in a 360 degree manner (paragraph 0027). At the time the invention was made, it would have been obvious to one of ordinary skill in

the art to incorporate the ground plane that completely encloses the die in a 360 degree manner as taught by Takeuchi in-the circuit module of Oggioni et al., in order to create a complete EMI shield around the die (Oggioni et al., paragraph 0009).

Regarding claims 21, 23 and 27, Oggioni et al. as modified by Takeuchi discloses all the limitations of claims 3, 10 and 4, respectively. Oggioni et al. further disclose that the conductive ground plates that are disposed along the flat surface of the substrate define a separation distance between adjacent ground plates (see figure 2).

Regarding claims 22, 24 and 28, Oggioni et al. further disclose that the separation distance is less than one-half the length of an electromagnetic wave (although Oggioni et al. does not disclose the distance between the adjacent ground plates, this distance will have to be less than one-half of some electromagnetic wave since electromagnetic waves can exist in any wavelength, see attached description of Electromagnetic waves from The Hutchinson Encyclopedia, from Helicon Publishing Limited, 2001.)

Regarding claim 30, Oggioni et al. further disclose (Fig. 3), that the heat spreader comprises: a primary portion (305) extending along the flat surface of the substrate in a substantially parallel manner relative to the flat surface of the substrate; and a secondary portion (201) extending from the primary portion toward the substrate along a direction substantially perpendicular to the flat surface of the substrate, the secondary portion (201) electrically contacting (via solder balls (203)) the conductive ground plane disposed along a flat surface of the substrate.

6. Claim 9 rejected under 35 U.S.C. 103(a) as being unpatentable over Oggioni et al. in view of Takeuchi as applied to claim 8 above, and further in view of Lee et al. (PGPub US 2004/0150102 A1).

Oggioni as modified by Takeuchi satisfies all the limitations of claim 8, and further disclose electrically conductive material which forms an electromagnetic interference seal between the main portion of the heat spreader and the conductive ground plane of the heat spreader interface. However, Oggioni et al does not disclose electrically conductive material between the edge portion of the heat spreader and the conductive ground edge of the heat spreader interface. Lee et al. discloses electrically conductive material, which forms an electromagnetic interference seal between the edge portion of the heat spreader and the conductive ground edge of the heat spreader interface (figure 5, paragraph 0029). At the time the invention was made, it would have been obvious to one of ordinary skill in the art to incorporate the electrically conductive material between the edge portion of the heat spreader and the conductive ground edge of the heat spreader interface, as taught by Lee et al., in the circuit board component disclosed by Oggioni et al. in order to create a complete EMI shield around the die (Oggioni et al., paragraph 0009).

*Allowable Subject Matter*

7. Claim 31 is objected to as being dependent upon a rejected base claim, but would be allowable if rewritten in independent form including all of the limitations of the base claim and any intervening claims.

The following is a statement of reasons for the indication of allowable subject matter:  
claim 31 recites the limitations, which have not been taught by the art of record: “a conductive ground edge extending from the secondary portion along a direction substantially perpendicular to the flat surface of the substrate and overhanging an outer periphery of the substrate, the conductive ground edge electrically coupled to a conductive ground edge portion of the heat spreader interface that extends along the outer periphery of the substrate”.

***Response to Arguments***

8. Applicant's arguments have been fully considered but they are not persuasive. Applicant has amended independent claims by introducing limitations of previously rejected claim 13. Limitations of claim 13 have been met by the references of record, as it was shown in the final Office action and reiterated in the instant Office action. Further, introduction of limitations “Application Specific Integrated Circuit” does nothing to distinguish the present invention over the art of record, since any integrated circuit eventually is used in a specific application and , therefore, is “application specific”. Further, Applicant contends that Oggioni does not teach that “the dielectric layer and the stiffener material forming part of the integrated circuit itself”. Examiner would like to direct the Applicant’s attention that such language is not present in the claims. On the other hand all of the claims limitations, which are present in the claims have been met by the references applied, as shown in the body of the rejection.

Therefore, the rejection is believed to be appropriate and is hereby maintained.

***Conclusion***

9. Any inquiry concerning this communication or earlier communications from the examiner should be directed to Anatoly Vortman whose telephone number is 571-272-2047. The examiner can normally be reached on Monday-Friday, between 10:00 am and 6:30 pm..

If attempts to reach the examiner by telephone are unsuccessful, the examiner's supervisor, Ms. Lynn Feild can be reached on 571-272-2092. The fax phone number for the organization where this application or proceeding is assigned is 571-273-8300.

Information regarding the status of an application may be obtained from the Patent Application Information Retrieval (PAIR) system. Status information for published applications may be obtained from either Private PAIR or Public PAIR. Status information for unpublished applications is available through Private PAIR only. For more information about the PAIR system, see <http://pair-direct.uspto.gov>. Should you have questions on access to the Private PAIR system, contact the Electronic Business Center (EBC) at 866-217-9197 (toll-free). If you would like assistance from a USPTO Customer Service Representative or access to the automated information system, call 800-786-9199 (IN USA OR CANADA) or 571-272-1000.

Anatoly Vortman  
Primary Examiner  
Art Unit 2835

AV

